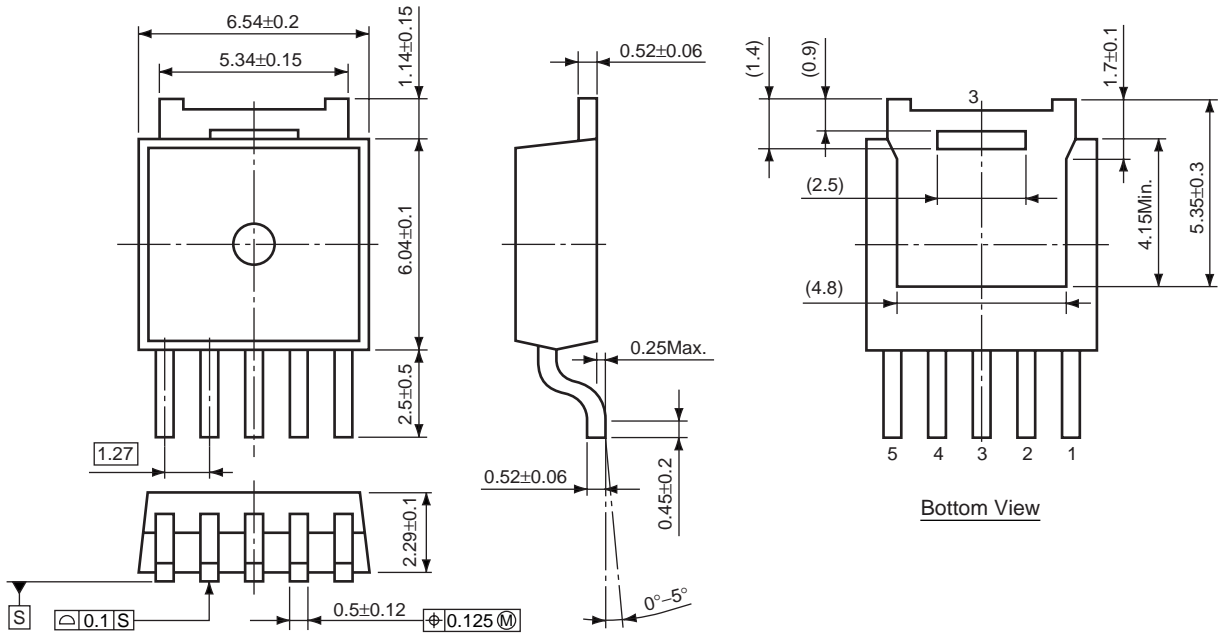


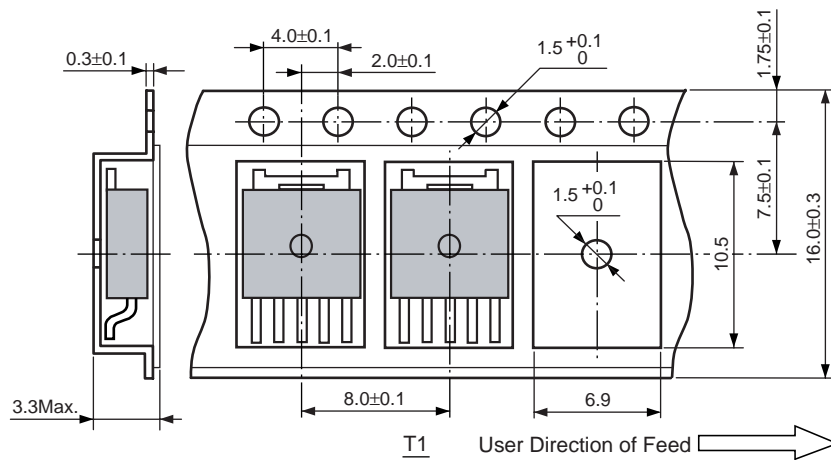
• TO-252-5-P1

Unit: mm

PACKAGE DIMENSIONS

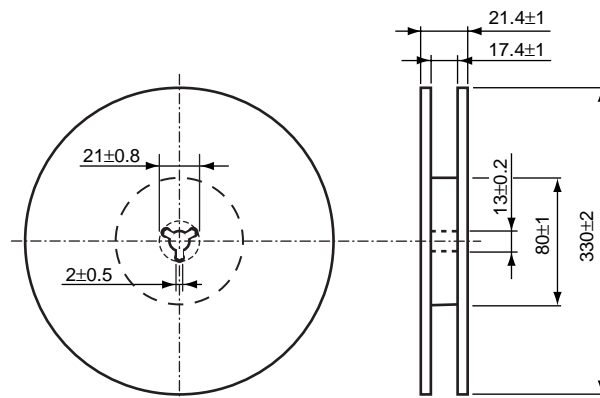


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-16Dc)

(1reel=3,000pcs)



POWER DISSIPATION (TO-252-5-P1)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

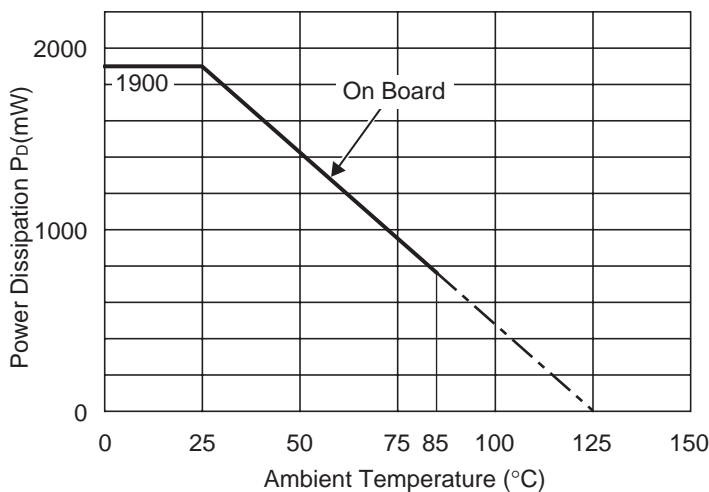
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	50mm × 50mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.5mm × 24pcs

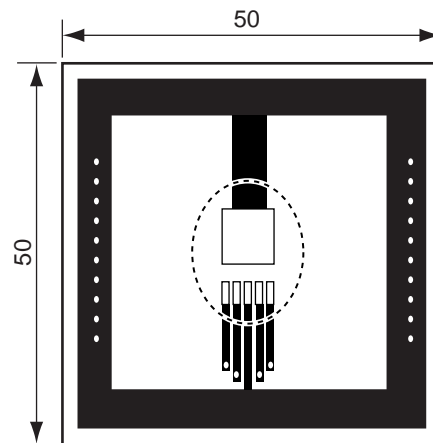
Measurement Results

($T_{opt}=25^{\circ}\text{C}$, $T_{jmax}=125^{\circ}\text{C}$)

	Standard Land Pattern
Power Dissipation	1900mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/1.9\text{W}=53^{\circ}\text{C/W}$
	$\theta_{jc}=17^{\circ}\text{C/W}$



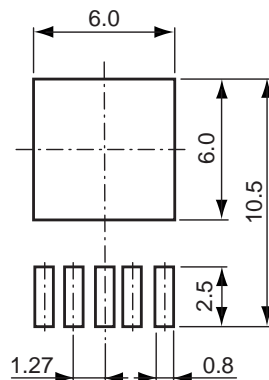
Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

RECOMMENDED LAND PATTERN



(Unit: mm)